HEF4077B

Quad 2-input EXCLUSIVE-NOR gate

Rev. 6 — 10 December 2015 Product data sheet

1. General description

The HEF4077B is a quad 2-input EXCLUSIVE-NOR gate. The outputs are fully buffered for the highest noise immunity and pattern insensitivity to output impedance.

The HEF4077B operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD}, V_{SS}, or another input.

2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from −40 °C to +85 °C
- Complies with JEDEC standard JESD 13-B

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
HEF4077BT	−40 °C to +85 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1

4. Functional diagram

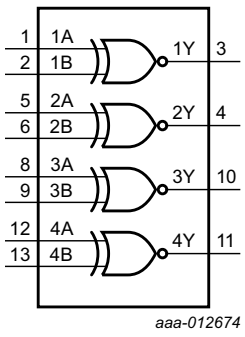


Fig 1. Functional diagram

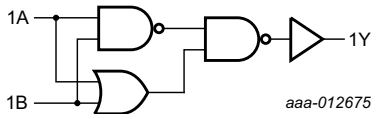


Fig 2. Logic diagram (one gate)

5. Pinning information

5.1 Pinning

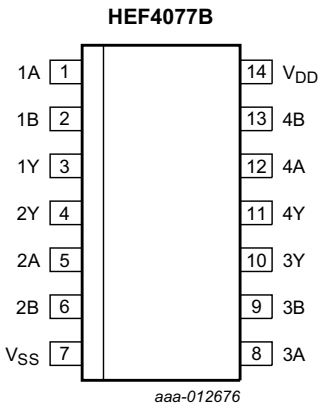


Fig 3. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A to 4A	1, 5, 8, 12	input
1B to 4B	2, 6, 9, 13	input
1Y to 4Y	3, 4, 10, 11	output
V_{SS}	7	ground (0 V)
V_{DD}	14	supply voltage

6. Functional description

Table 3. Functional table[1]

Input		Output
nA	**nB**	**nY**
L	L	H
L	H	L
H	L	L
H	H	H

[1] H = HIGH voltage level; L = LOW voltage level.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to V_{SS} = 0 V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		−0.5	+18	V
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	±10	mA
V_I	input voltage		−0.5	$V_{DD} + 0.5$	V
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{DD} + 0.5$ V	-	±10	mA
$I_{I/O}$	input/output current		-	±10	mA
I_{DD}	supply current		-	50	mA
T_{stg}	storage temperature		−65	+150	°C
T_{amb}	ambient temperature		−40	+85	°C
P_{tot}	total power dissipation	T_{amb} = −40 °C to + 85 °C			
		SO14 [1]	-	500	mW
P	power dissipation	per output	-	100	mW

[1] For SO14 packages: above T_{amb} = 70 °C, P_{tot} derates linearly with 8 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		3	15	V
V_I	input voltage		0	V_{DD}	V
T_{amb}	ambient temperature	in free air	−40	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{DD} = 5 V	-	3.75	µs/V
		V_{DD} = 10 V	-	0.5	µs/V
		V_{DD} = 15 V	-	0.08	µs/V

9. Static characteristics

Table 6. Static characteristics

V_{SS} = 0 V; V_I = V_{SS} or V_{DD}; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	T_{amb} = –40 °C		T_{amb} = +25 °C		T_{amb} = +85 °C		Unit
				Min	Max	Min	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$\|I_O\|$ < 1 µA	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
V_{IL}	LOW-level input voltage	$\|I_O\|$ < 1 µA	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V
V_{OH}	HIGH-level output voltage	$\|I_O\|$ < 1 µA	5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
V_{OL}	LOW-level output voltage	$\|I_O\|$ < 1 µA	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
I_{OH}	HIGH-level output current	V_O = 2.5 V	5 V	-	–1.7	-	–1.4	-	–1.1	mA
		V_O = 4.6 V	5 V	-	–0.52	-	–0.44	-	–0.36	mA
		V_O = 9.5 V	10 V	-	–1.3	-	–1.1	-	–0.9	mA
		V_O = 13.5 V	15 V	-	–3.6	-	–3.0	-	–2.4	mA
I_{OL}	LOW-level output current	V_O = 0.4 V	5 V	0.52	-	0.44	-	0.36	-	mA
		V_O = 0.5 V	10 V	1.3	-	1.1	-	0.9	-	mA
		V_O = 1.5 V	15 V	3.6	-	3.0	-	2.4	-	mA
I_I	input leakage current		15 V	-	±0.3	-	±0.3	-	±3.0	µA
I_{DD}	supply current	all valid input combinations; I_O = 0 A	5 V	-	1.0	-	1.0	-	7.5	µA
			10 V	-	2.0	-	2.0	-	15.0	µA
			15 V	-	4.0	-	4.0	-	30.0	µA
C_I	input capacitance			-	-	-	7.5	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

T_{amb} = 25 °C; waveforms see Figure 4; test circuit, see Figure 5; unless otherwise specified. [1]

Symbol	Parameter	Conditions	V_{DD}	Extrapolation formula	Min	Typ	Max	Unit
t_{PHL}	HIGH to LOW propagation delay	nA or nB to nY	5 V	48 ns + (0.55 ns/pF)C_L	-	75	150	ns
			10 V	24 ns + (0.23 ns/pF)C_L	-	35	70	ns
			15 V	22 ns + (0.16 ns/pF)C_L	-	30	55	ns
t_{PLH}	LOW to HIGH propagation delay	nA or nB to nY	5 V	43 ns + (0.55 ns/pF)C_L	-	70	145	ns
			10 V	19 ns + (0.23 ns/pF)C_L	-	30	60	ns
			15 V	17 ns + (0.16 ns/pF)C_L	-	25	50	ns
t_t	transition time		5 V [2]	10 ns + (1.00 ns/pF)C_L	-	60	120	ns
			10 V	9 ns + (0.42 ns/pF)C_L	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C_L	-	20	40	ns

[1] The typical value of the propagation delay and output transition time can be calculated with the extrapolation formula (C_L in pF).

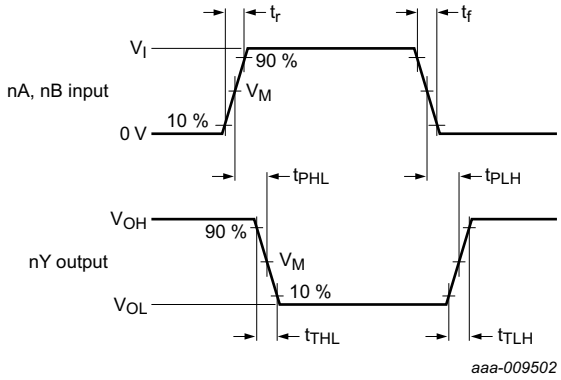
[2] t_t is the same as t_{THL} and t_{TLH}.

Table 8. Dynamic power dissipation

V_{SS} = 0 V; $t_r = t_f \leq 20$ ns; T_{amb} = 25 °C.

Symbol	Parameter	V_{DD}	Typical formula	where:
P_D	dynamic power dissipation	5 V	$P_D = 850 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	f_i = input frequency in MHz; f_o = output frequency in MHz; C_L = output load capacitance in pF; $\Sigma(f_o \times C_L)$ = sum of the outputs; V_{DD} = supply voltage in V.
		10 V	$P_D = 4500 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	
		15 V	$P_D = 114700 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	

11. Waveforms



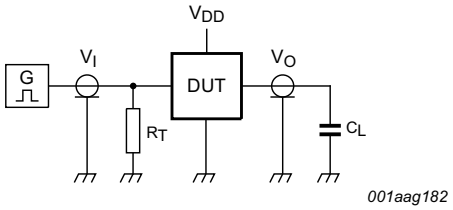
Measurement points are given in Table 9.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 4. Input to output propagation delay and output transition times

Table 9. Measurement points

Supply voltage	Input	Output
V_{DD}	V_M	V_M
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$



Test data is given in Table 10.

Definitions for test circuit:

DUT = Device Under Test.

C_L = load capacitance including jig and probe capacitance.

R_T = termination resistance should be equal to the output impedance Z_o of the pulse generator.

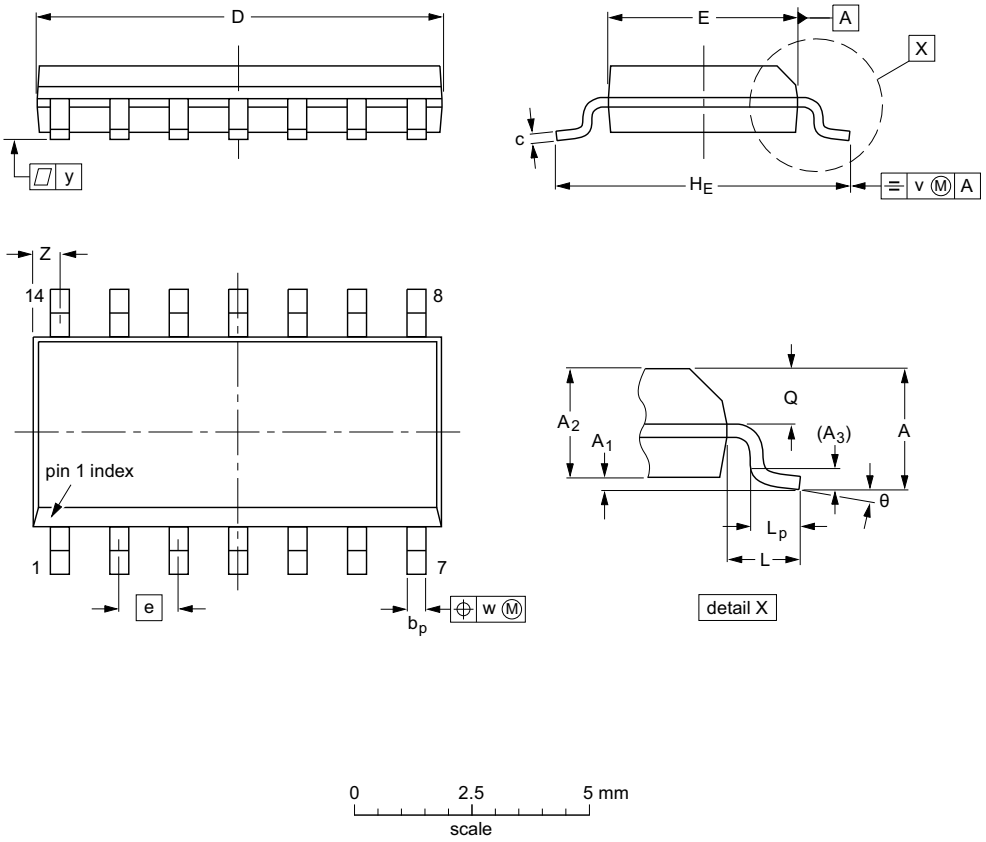
Fig 5. Test circuit

Table 10. Test data

Supply voltage	Input		Load
V_{DD}	V_I	t_r, t_f	C_L
5 V to 15 V	V_{SS} or V_{DD}	≤ 20 ns	50 pF

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm **SOT108-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT108-1	076E06	MS-012				~~99-12-27~~ 03-02-19

Fig 6. Package outline SOT108-1 (SO14)

13. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged-Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4077B v.5	20151210	Product data sheet	-	HEF4077B v.4
Modifications:	• Type number HEF4077BP (SOT27-1) removed.			
HEF4077B v.4	20140718	Product data sheet	-	HEF4077B_CNV_3
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Data sheet is imported into latest template.			
HEF4077B_CNV_3	19950101	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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